

Date: Wed Nov 28 00:11:13 2018
Customer Name: MISTRAL SOLUTIONS PVT LTD
Customer P/N: J7 SOM
Customer Rev:
Customer Mat: I-SPEED
Plant: Wuxi
Cat/Tool Num: RFS_0296



SANMINA

Lay #	Thick (in)	Picture	Type Dk Df	Description	Drill Picture
0.0006/0.0013			4.5 0.019	Soldermask	
1	0.0018		F / S	0.333oz w/plating	
	0.0044		2.94 0.0058	fill	
2	0.0013		P	1oz	
	0.0040		3.34 0.0060	core	
3	0.0013		S	1oz	
	0.0042		3.20 0.0059	fill	
4	0.0013		P	1oz	
	0.0040		3.34 0.0060	core	
5	0.0013		S	1oz	
	0.0042		3.20 0.0059	fill	
6	0.0013		P	1oz	
	0.0040		3.34 0.0060	core	
7	0.0013		S	1oz	
	0.0042		3.20 0.0059	fill	
8	0.0013		P	1oz	
	0.0040		3.34 0.0060	core	
9	0.0013		P	1oz	
	0.0042		3.20 0.0059	fill	
10	0.0013		S	1oz	
	0.0040		3.34 0.0060	core	
11	0.0013		P	1oz	
	0.0042		3.20 0.0059	fill	
12	0.0013		S	1oz	
	0.0040		3.34 0.0060	core	
13	0.0013		P	1oz	
	0.0042		3.20 0.0059	fill	
14	0.0013		S	1oz	
	0.0040		3.34 0.0060	core	
15	0.0013		P	1oz	
	0.0044		2.94 0.0058	fill	
16	0.0018		F / S	0.333oz w/plating	
0.0006/0.0013			4.5 0.019	Soldermask	
0.0840	Total thickness (in) Over mask on plated copper				
0.0800	After lamination thickness (in)				
0.0819	Over laminate thickness (in) (with soldermask)				
0.0834	Customer Requirement (in)				
+/-0.0083	Customer Tolerance (in)				

Notes and Recommendations:

- 1. Assume copper rate 80% for power ground layer, 30% for single layer
 - 2. Can not meet 66ohms single ended & 132ohms diff ended, suggest ignore these impedance requirement
- Trace widths measured at base of trace
All dimensions in inches (unless otherwise noted)

Products built using these specified nominal dimensions will have variation in physical and electrical results based on acceptable manufacturing materials and process tolerance.
This data is intended to provide one possible solution to meet a particular set of impedance and thickness requirements.
If any of these values are attached to fabrication prints, they should be marked as 'reference'.